

L Number	Hits	Search Text	DB	Time stamp
-	2	float and zervigon.xa.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 10:26
-	26067	float\$ same (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 17:26
-	596507	((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 17:29
-	5524	(float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 10:25
-	21	((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.)))) and "first electrode" and DC and AC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 17:33
-	15	((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.)))) and "upper electrode" and DC and AC not (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.)))) and "first electrode" and DC and AC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 17:40
-	28	((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.)))) and (electrode same (DC and AC) not (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.)))) and "first electrode" and DC and AC) or (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.)))) and "upper electrode" and DC and AC not (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.)))) and "first electrode" and DC and AC)))) and "first electrode" and DC and AC))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 17:53

81	((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and (electrode and (DC and AC)) not (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and "first electrode" and DC and AC) or (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and "upper electrode" and DC and AC not (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and "first electrode" and DC and AC) or (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and (electrode same (DC and AC)) not (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and "first electrode" and DC and AC) or (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and "upper electrode" and DC and AC not (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and "first electrode" and DC and AC))))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 18:03
172	("floating wafer" or "floating substrate") and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 18:04
76	("floating wafer" or "floating substrate") and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 18:04
0	5980687.pn. and bias	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 08:58
2	5980687.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 10:25
5524	(float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.))))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 10:29
1366	((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 10:51
0	((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and AC and DC and "zero bias"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 10:52
4	((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and "zero bias"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 10:52

-	111	(((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and AC and DC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:51
-	24	(((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and AC and DC) and switch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:56
-	2	5897752.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:56
-	6	((("5316646") or ("5316645") or ("5202008") or ("5114556") or ("4038171") or ("3410775")).PN.	USPAT	2002/08/21 11:59
-	87	(((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and AC and DC) not (((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and AC and DC) and switch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 12:00
-	168	(((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and switch not (((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$.CCLS. OR (118/\$.CCLS. OR (438/\$.CCLS. OR (427/\$.CCLS. OR (219/\$.CCLS.)))) and AC and DC) and switch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 14:02
-	2	6220201.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 14:25
-	9	((("6033482") or ("6406925") or ("5942042") or ("6346428") or ("5897752") or ("6379576") or ("6237527") or ("6220201") or ("5980687") or ("5980687")).PN.	USPAT	2002/08/21 14:25
-	2	5980687.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 10:39
-	1	us-20030017709-\$.did.	USPAT; US-PGPUB;	2003/02/06 12:06
-	3265	(wafer or substrate) same (conduction and interface)	EPO; JPO; DERWENT; IBM_TDB	2003/02/06 12:07
-	1271	(wafer or substrate) with (conduction and interface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 12:08
-	78	(wafer or substrate) with (conduction and interface and roughness)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 12:14
-	1	us-20030017709-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 12:22

-	2	5810933.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 13:12
-	2	5980687.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 13:53
-	1974	((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 13:57
-	1113	((((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)) and upper and lower	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 13:59
-	864	(((((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)) and upper and lower) and (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 13:59
-	807	(((((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)) and upper and lower) and (wafer or substrate)) and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 14:00
-	403	((((((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)) and upper and lower) and (wafer or substrate)) and power) and khz and mhz	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 14:03
-	74	((((((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)) and upper and lower) and (wafer or substrate)) and power) and khz and mhz) and (118/723e.ccls. or 156/345.43.ccls. or 156/345.44.ccls. or 156/345.46.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 14:46
-	2	5810933.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 14:46